

Product features

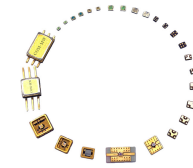
High precision FBAR process,

Small size, high performance, but sensitive to static electricity.

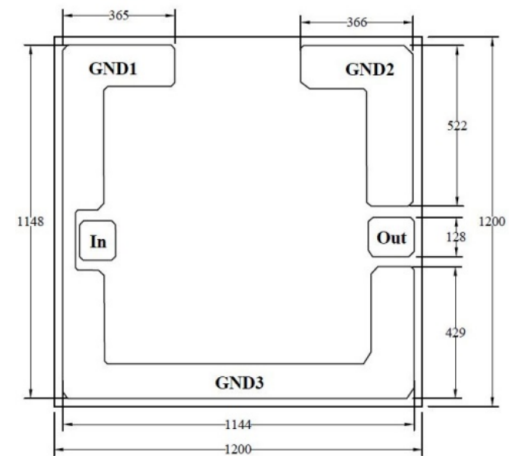
Main specifications

Parameters	Frequency	/	Min	Typical	Max	Units
Passband	/	/		1800		MHz
Center loss	/	/		2.0	2.5	dB
-1.0dB BW	/	/		point frequency		MHz
Rejection	1.7	GHz $\geq$	40	55		dB
Rejection	1.9	GHz $\geq$	40	55		dB
Passband VSWR	/	/			2.0	

Reference picture



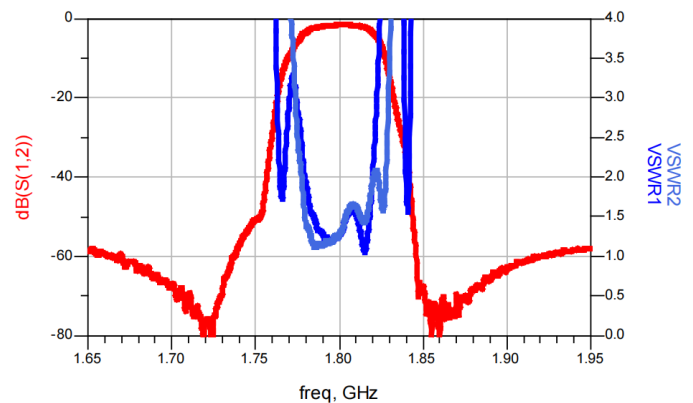
外形结构图 (um)



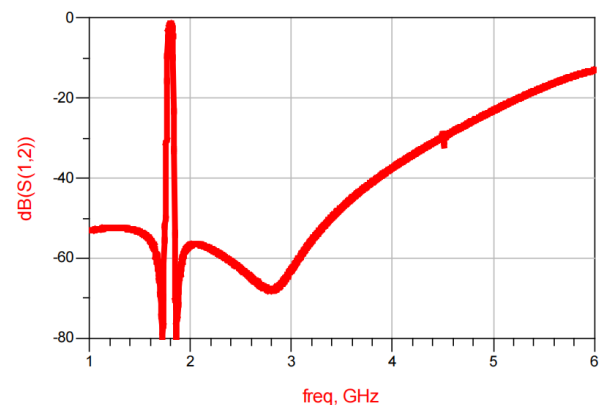
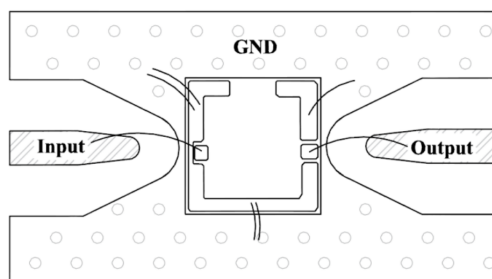
Other parameters

Connector	Microstrip pad
Impedance	50 Ω
Operation Temp.	-55~+85°C Design assurance
Storage Temp.	-55~+125°C Design assurance
Quality Grade	Industrial grade
ROHS	Compliant Available
Filter Category	FBAR

Typical test curve



Assembly diagram

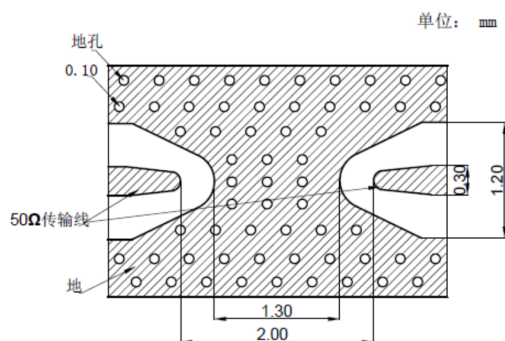


Note: The specifications and performance data contained in this data sheet are based on tests established by CMW.

Assembly instructions

1. The chip needs to be sealed and stored in a nitrogen cabinet. After opening, please use it within 3 days. The chip needs to be assembled and used in a purified environment, and the chip ports are interchangeable,
2. The chip needs to be clamped on both sides with precision pointed tweezers to avoid touching the surface of the chip. It is recommended to use low stress adhesive (preferably ME8456-DA) to bond the bottom of the chip, with an appropriate amount of adhesive to avoid excessive contamination of the front graphics,
3. After the chip is bonded, it can be cleaned using a plasma cleaning machine to avoid ultrasonic cleaning and liquid cleaning,
4. The performance of chips is affected by packaging form, wire specifications, length, and position. Please refer to the assembly diagram and consult the supplier. It is recommended to use wire bonding with a diameter of 25 μ m.

Suggested PCB Layout



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